

Intel® SCH US15WP

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Specifications	
Essentials	
Status	Launched
Launch Date	Q1'09
Supported FSBs	400MHz / 533MHz
FSB Parity	No
Embedded Options Available	Yes
Lithography	130 nm
TDP	2.3 W
Recommended Customer Price	N/A
Datasheet	Link
Memory Specifications	
Max Memory Size (dependent on memory type)	2 GB
Memory Types	DDR2 400/533
Max # of Memory Channels	1
Physical Address Extensions	32-bit
ECC Memory Supported ‡	No
Graphics Specifications	
Integrated Graphics †	Yes
Graphics Output	LVDS, SDVO
# of Displays Supported †	2
Macrovision* License Required	No
Expansion Options	
PCI Support	None
PCI Express Revision	1.1
PCI Express Configurations †	2x1
Max # of PCI Express Lanes	2
I/O Specifications	
USB Revision	USB 2.0
# of USB Ports	8
Total # of SATA Ports	0
Integrated LAN	None
Integrated IDE	Yes
Package Specifications	
Max CPU Configuration	1
T _{CASE}	85°C
Package Size	37.5mm x 37.5mm
Low Halogen Options Available	See MDDS
Advanced Technologies	
Intel® ME Firmware Version	No
Intel® Quick Resume Technology	No
Intel® Quiet System Technology	No
Intel® HD Audio Technology	Yes
Intel® AC97 Technology	No
Intel® Matrix Storage Technology	No
Intel® Platform Protection Technology	
Trusted Execution Technology ‡	No

Related Products

Products formerly Poulsbo



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PCN/MDDS Information

SLGQA
901752: PCN | MDDS

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Refer to Datasheet for formal definitions of product properties and features.

*Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet J5-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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